

## Description

The ACE2301 is the P-Channel logic enhancement mode power field effect transistor are produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and Battery powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

## Features

- $V_{DS} = -20V$
- $R_{DS(ON)}, V_{GS} @ -4.5V, I_{DS} @ -2.8A = 100m\Omega$
- $R_{DS(ON)}, V_{GS} @ -2.5V, I_{DS} @ -2.0A = 150m\Omega$
- Advanced trench process technology
- High Density Cell Design For Ultra Low On-Resistance

## Absolute Maximum Ratings

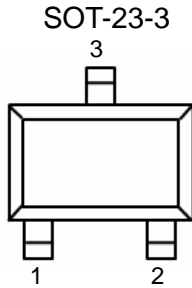
Parameter	Symbol	Max	Unit	
Drain-Source Voltage	$V_{DS}$	-20	V	
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V	
Continuous Drain Current	$I_D$	-2.2	A	
Pulsed Drain Current <sup>1)</sup>	$I_{DM}$	-8	A	
Maximum Power Dissipation	$P_D$	$T_A = 25^\circ C$	1.25	W
		$T_A = 70^\circ C$	0.8	
Operating Junction Temperature	$T_J$	-55 to 150	$^\circ C$	
Storage Temperature Range	$T_{STG}$	-55 to 150	$^\circ C$	
Junction to Ambient Thermal Resistance (PCB mounted) <sup>2)</sup>	$R_{\theta JA}$	140	$^\circ C/W$	

Note: 1.Repetitive Rating: Pulse width limited by the maximum junction temperature.

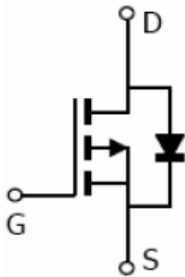
2.1-in<sup>2</sup> 2oz Cu PCB board.

3.Guaranteed by design; not subject to production testing.

## Packaging Type



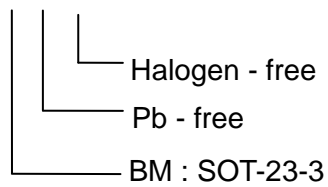
Pin	Symbol	Description
1	G	Gate
2	S	Source
3	D	Drain



## Ordering information

### Selection Guide

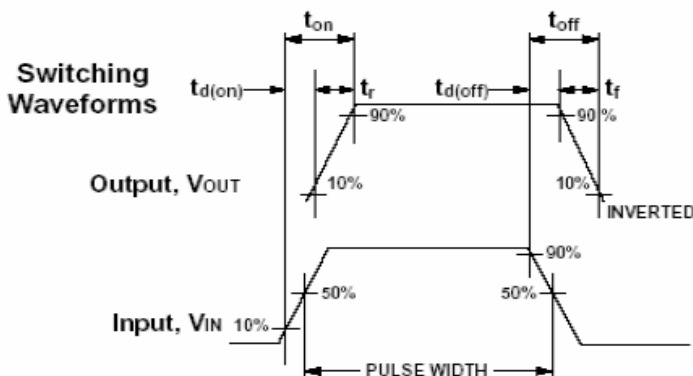
ACE2301 XX + H



## Electrical Characteristics

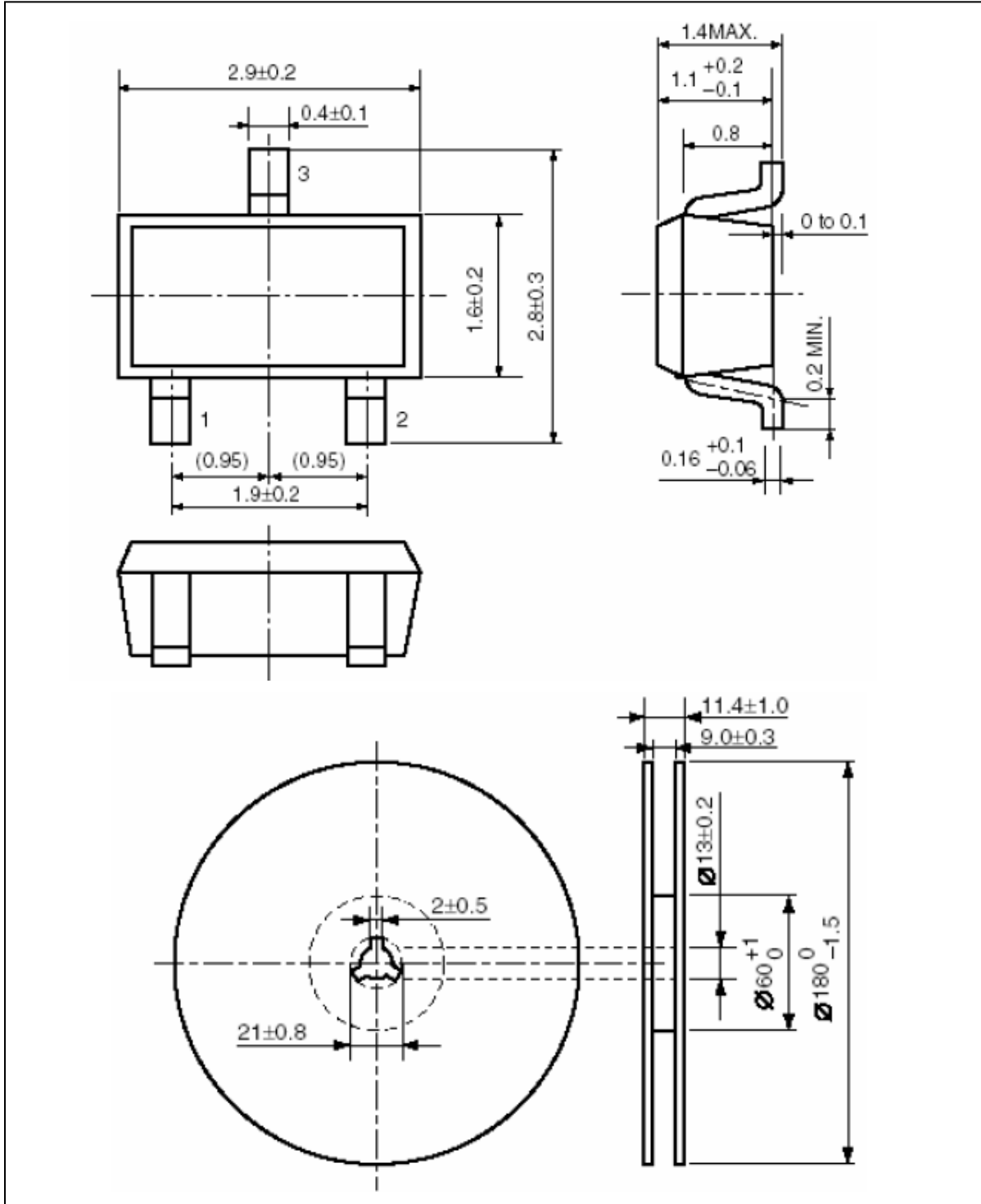
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	-20			V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_D=-2.8A$		70.0	100.0	m $\Omega$
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=-2.5V, I_D=-2.0A$		85.0	150.0	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	-0.4		-0.9	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-9.6V, V_{GS}=0V$			-1	$\mu A$
Gate Body Leakage	$I_{GSS}$	$V_{GS}=\pm 8V, V_{DS}=0V$			$\pm 100$	nA
Forward Trans conductance	$G_{fs}$	$V_{DS}=-5V, I_D=-2.8A$		6.5		S
Dynamic <sup>3)</sup>						
Total Gate Charge	$Q_g$	$V_{DS}=-6V, I_D=-2.8A$ $V_{GS}=-4.5V$		5.8	10	nC
Gate-Source Charge	$Q_{gs}$			0.85		
Gate-Drain Charge	$Q_{gd}$			1.7		
Turn-On Delay Time	$T_{d(on)}$	$V_{DD}=-6V, R_L=6\Omega$ $I_D=-1A, V_{GEN}=-4.5V$ $R_G=6\Omega$		13	25	ns
Turn-On Rise Time	$T_f$			36	60	
Turn-Off Delay Time	$t_{d(off)}$			42	70	
Turn-Off Fall Time	$t_f$			34	60	
Input Capacitance	$C_{iss}$	$V_{DS}=-6V, V_{GS}=0V$ $F=1.0MHz$		415		pF
Output Capacitance	$C_{oss}$			223		
Reverse Transfer Capacitance	$C_{rss}$			87		
Source-Drain Diode						
Max. Diode Forward Current	$I_S$				-1.6	A
Diode Forward Voltage	$V_{SD}$	$I_S=-1.6A, V_{GS}=0V$			-1.2	V

Note: Pulse test pulse width $\leq$ 300us, duty cycle $\leq$ 2%.



Packing Information

SOT-23-3



## Notes

ACE does not assume any responsibility for use as critical components in life support devices or systems without the express written approval of the president and general counsel of ACE Electronics Co., LTD. As sued herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.